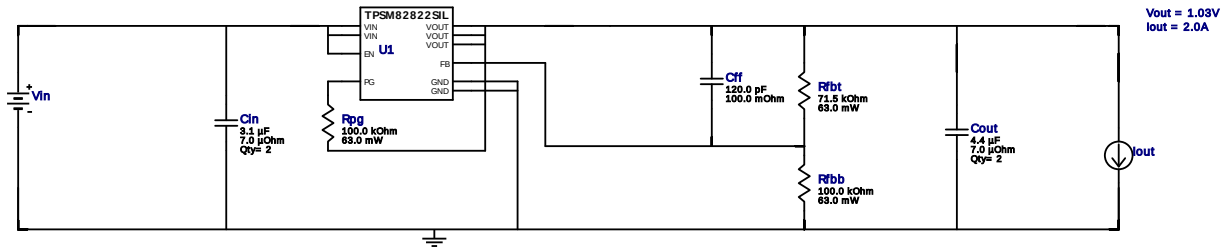
WEBENCH® Design Report

VinMin = 3.5V
VinMax = 3.9V
Vout = 1.03V
Iout = 2.0A

Device = TPSM82822SILR
Topology = Buck
Created = 2020-07-27 00:12:15.359
BOM Cost = $3.80
BOM Count = 9
Total Pd = 0.55W

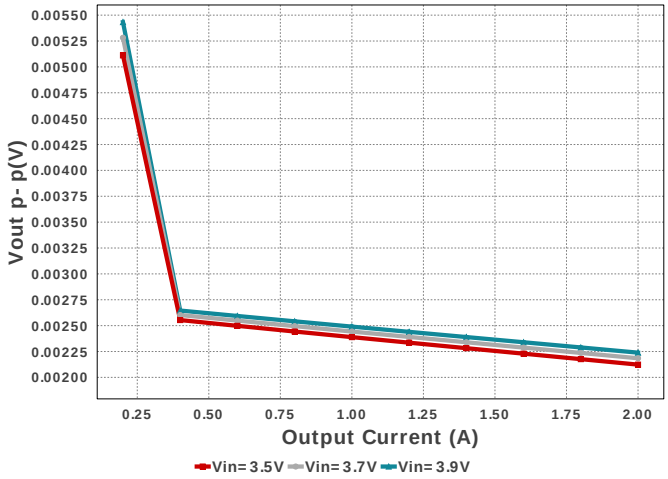
Design : 26 TPSM82822SILR
TPSM82822SILR 3.5V-3.9V to 1.03V @ 2A



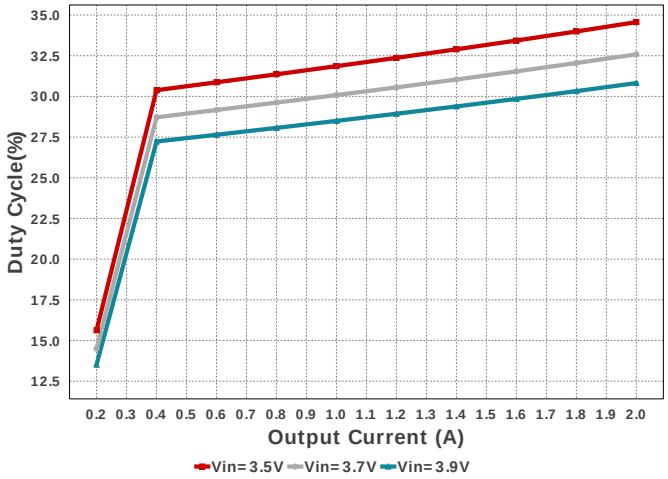
Electrical BOM

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cff	KOA	GRM0335C1H121JA01D Series= X7R	Cap= 120.0 pF ESR= 100.0 mOhm VDC= 25.0 V IRMS= 0.0 A	1	$0.30	0201 3 mm^2
Cin	Murata	GRM188R61E475KE11D Series= X5R	Cap= 3.1 uF ESR= 7.0 uOhm VDC= 10.0 V IRMS= 11.43 A	2	$0.50	0805 6 mm^2
Cout	Murata	GRM188R61E475KE11D Series= X5R	Cap= 4.4 uF ESR= 7.0 uOhm VDC= 4.0 V IRMS= 6.0 A	2	$0.40	0402_070 5 mm^2
Rfbb	KOA	RK73H1ETTP1003F Series= CRCW..e3	Res= 100.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.30	0402 3 mm^2
Rfbt	KOA	RK73H1ETTP7152F Series= CRCW..e3	Res= 71.5 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.30	0402 3 mm^2
Rpg	KOA	RK73H1ETTP1003F Series= CRCW..e3	Res= 100.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	$0.10	0402 3 mm^2
U1	Texas Instruments	TPSM82822SILR	Switcher	1	$1.00	SIL0010D 10 mm^2

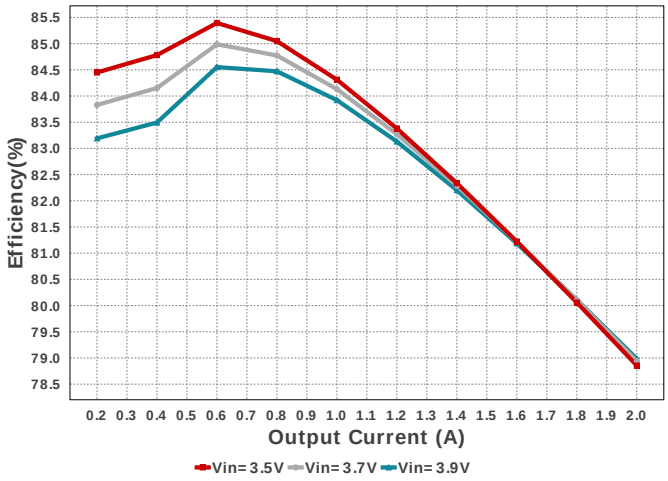
Vout p- p



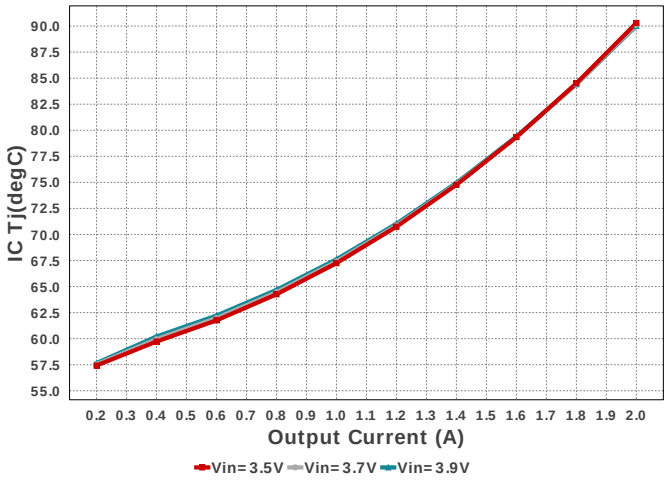
Duty Cycle



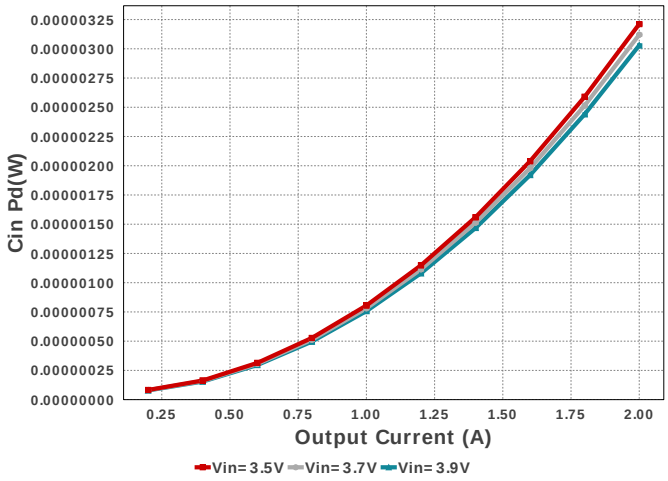
Efficiency



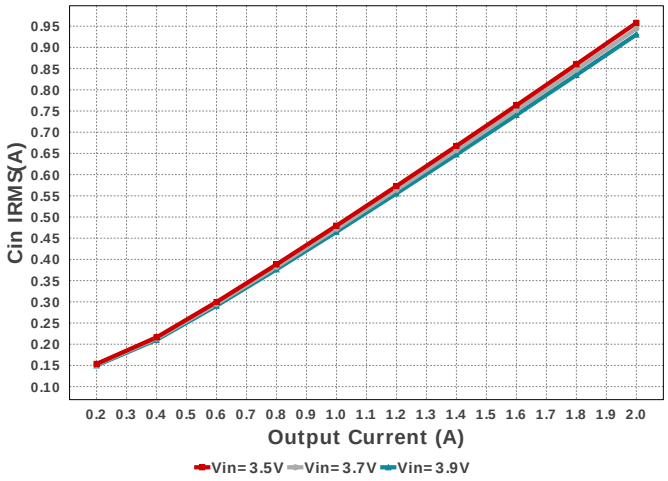
IC Tj

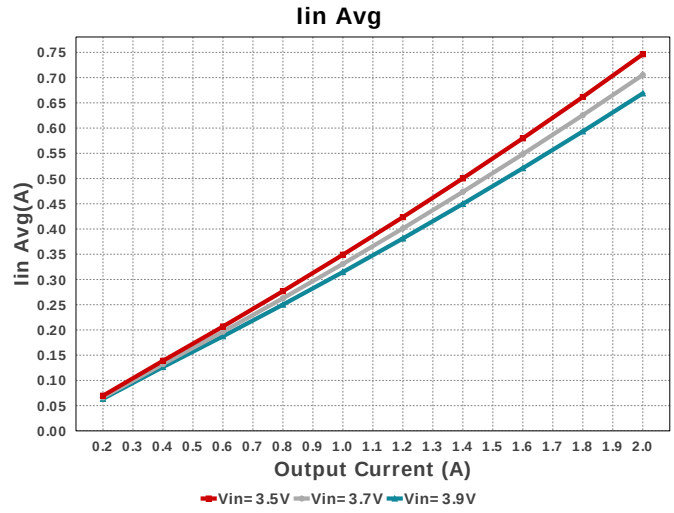


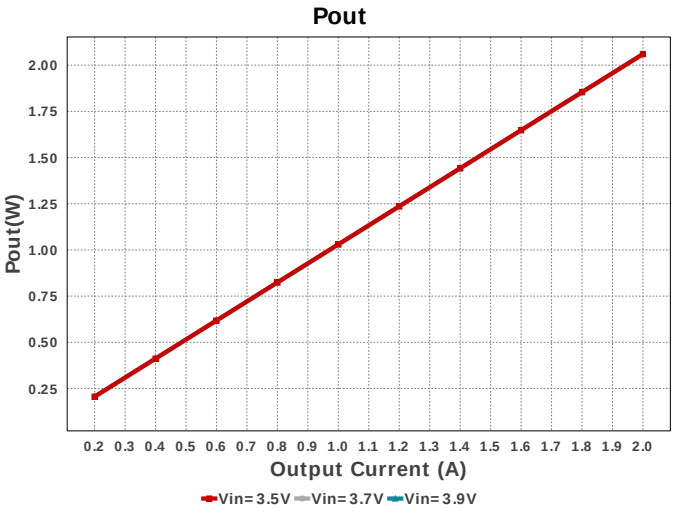
Cin Pd

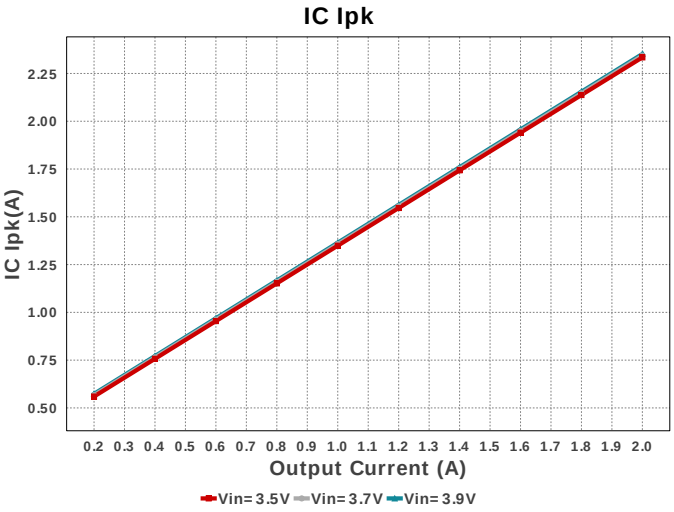


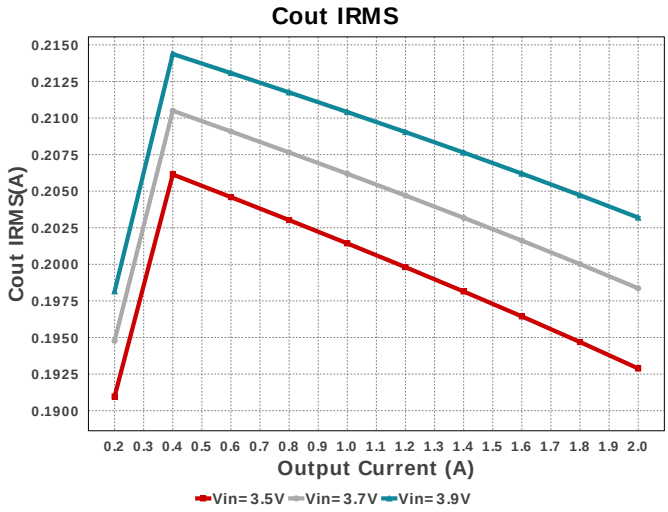
Cin IRMS

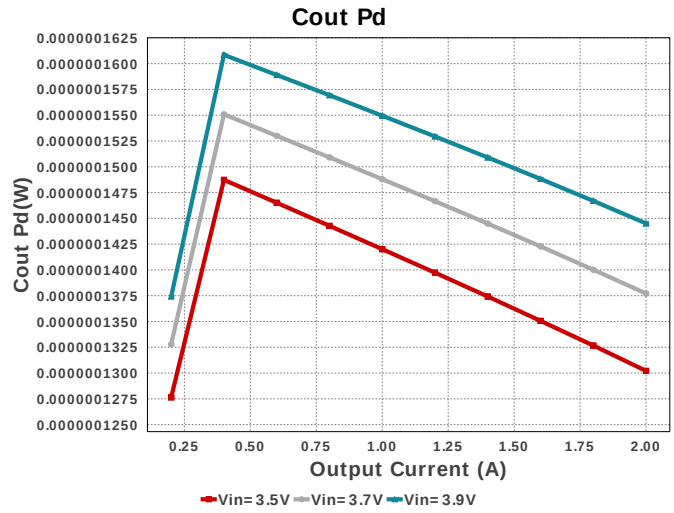


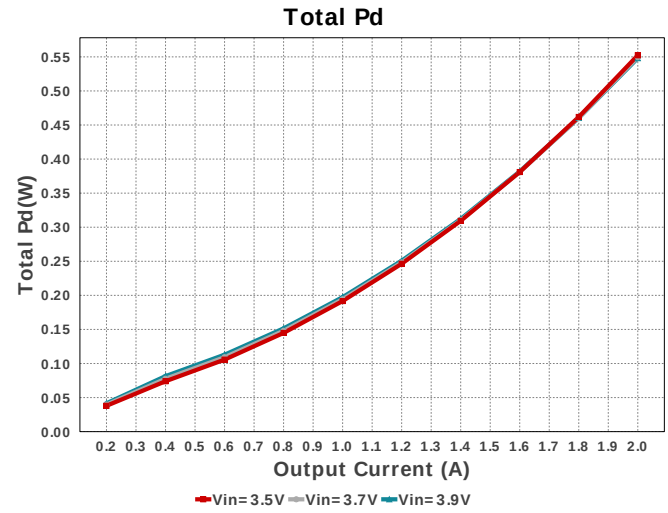


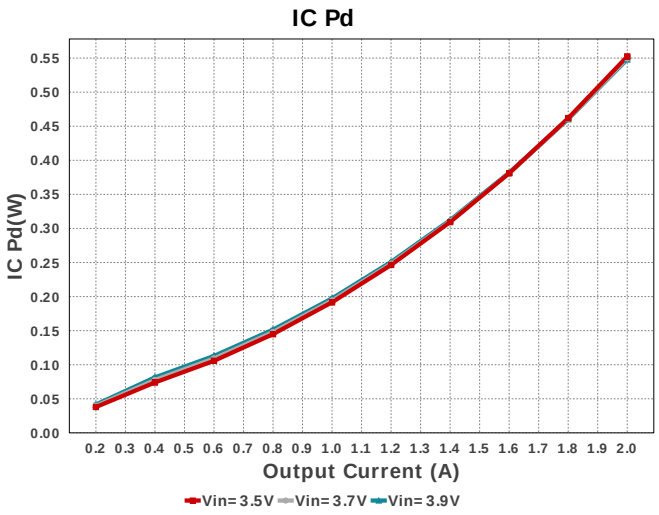


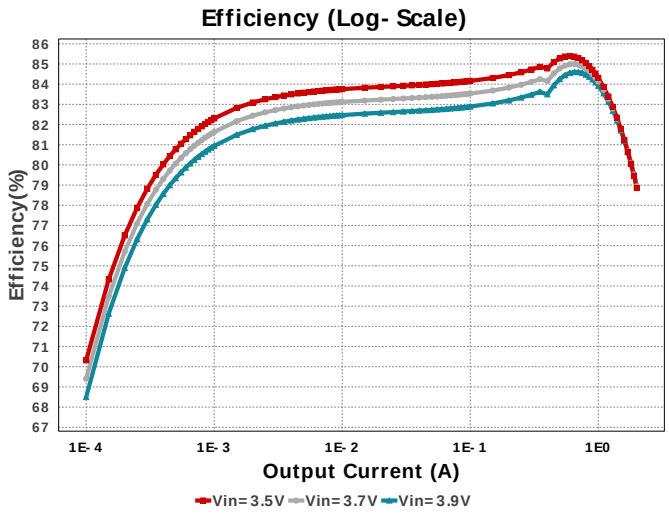












Operating Values

#	Name	Value	Category	Description
1.	BOM Count	9		Total Design BOM count
2.	Total BOM	$3.8		Total BOM Cost
3.	Cin IRMS	930.347 mA	Capacitor	Input capacitor RMS ripple current
4.	Cin Pd	3.029 µW	Capacitor	Input capacitor power dissipation
5.	Cout IRMS	203.196 mA	Capacitor	Output capacitor RMS ripple current
6.	Cout Pd	144.51 nW	Capacitor	Output capacitor power dissipation
7.	IC Ipk	2.352 A	IC	Peak switch current in IC
8.	IC Pd	548.09 mW	IC	IC power dissipation
9.	IC Tj	90.023 degC	IC	IC junction temperature
10.	ICThetaJA Effective	63.9 degC/W	IC	Effective IC Junction-to-Ambient Thermal Resistance
11.	Iin Avg	668.74 mA	IC	Average input current
12.	Cin Pd	3.029 µW	Power	Input capacitor power dissipation
13.	Cout Pd	144.51 nW	Power	Output capacitor power dissipation
14.	IC Pd	548.09 mW	Power	IC power dissipation
15.	Total Pd	548.089 mW	Power	Total Power Dissipation
16.	Duty Cycle	30.818 %	System Information	Duty cycle
17.	Efficiency	78.985 %	System Information	Steady state efficiency
18.	FootPrint	41.0 mm^2	System Information	Total Foot Print Area of BOM components
19.	Frequency	4.466 MHz	System Information	Switching frequency
20.	Iout	2.0 A	System Information	Iout operating point
21.	Mode	CCM	System Information	Conduction Mode
22.	Pout	2.06 W	System Information	Total output power
23.	Vin	3.9 V	System Information	Vin operating point
24.	Vout	1.03 V	System Information	Operational Output Voltage
25.	Vout Actual	1.029 V	System Information	Vout Actual calculated based on selected voltage divider resistors
26.	Vout Tolerance	1.851 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
27.	Vout p-p	2.239 mV	System Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	2.0	Maximum Output Current
VinMax	3.9	Maximum input voltage
VinMin	3.5	Minimum input voltage
Vout	1.03	Output Voltage
base_pn	TPSM82822	Base Product Number
source	DC	Input Source Type
Ta	55.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

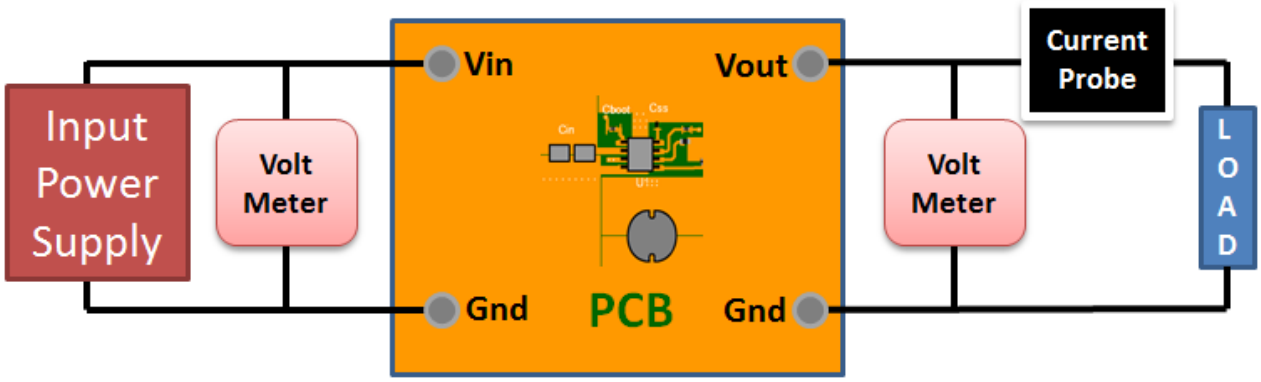
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 3.5V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum Iout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

1. Master key : 4B22EECAC03607DD[v1]
2. **TPSM82822** Product Folder : http://www.ti.com/product/TPSM82822 : contains the data sheet and other resources.